

**CLAIM SUMMARY:**

1. (Currently Amended) A method of manufacturing a contactless smart card including an integrated-circuit chip and an antenna, comprising: producing [in which] metallised protrusions [are produced] on two contact pads on the chip, said method including the step of connecting the chip to the antenna by embedding the metallised protrusions in [the] a thickness of the antenna, at the time that the chip is [attached] connected to the antenna.

2. (Currently Amended) [A] The method according to Claim 1, [wherein] comprising producing the antenna [is produced] from a material [that has] having a viscous state at the time that the chip is attached, to allow the embedding of the metallised protrusions.

3. (Currently Amended) [A] The method according to claim 1, [wherein] comprising producing the antenna [is produced] on an insulating substrate having [the] a form factor of [a] the smart card.

4. (Currently Amended) [A] The method according to claim 1, [wherein] comprising producing the antenna [is produced] from a thermoplastic material loaded with metallic particles and connecting the chip [is attached] to the antenna by thermocompression.

5. (Currently Amended) [A] ~~The~~ method according to claim 1, [wherein] comprising producing the antenna [is produced] from a non-polymerised conductive material and connecting the chip [is attached] to the antenna by compression, and further including the step of polymerizing the antenna material by applying heat [to polymerize the antenna material].

6. (Currently Amended) [A] ~~The~~ method according to claim 1, [wherein] comprising producing the antenna [is produced] from a moist conductive polymer material, and connecting the chip [is attached] to the antenna by compression.

7. (Currently Amended) [A] ~~The~~ method according to claim 1, [wherein] comprising producing the antenna [is produced] from a thermoplastic material loaded with metallic particles and gluing the chip [is glued] to an insulating sheet having the form factor of a smart card, and wherein the [connection] connecting of the chip to the antenna is effected by hot lamination.

8. (Currently Amended) [A] ~~The~~ method according to claim 1, wherein the metallised protrusions have a substantially conical shape.

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